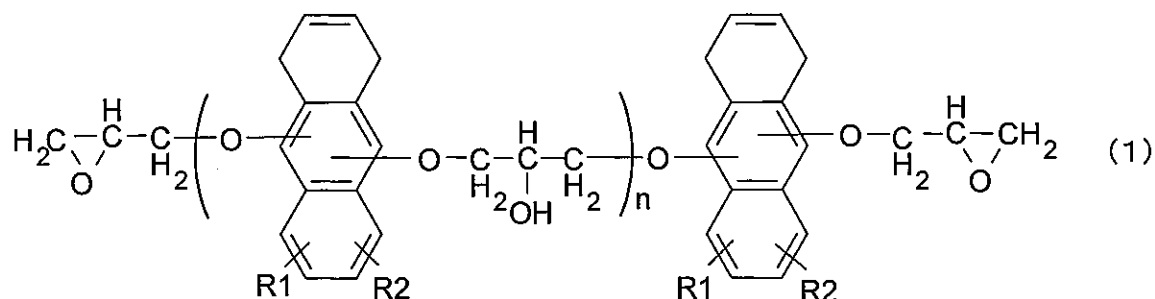


ABSTRACTS

The object of the invention is to provide a resin composition for semiconductor encapsulation realizing excellent soldering resistance and flame resistance and having excellent flowability and curing properties, and a semiconductor device. The invention has solved the object by a resin composition for semiconductor encapsulation comprising (A) an epoxy resin containing (a) an epoxy resin represented by formula (1), (B) a compound having two or more phenolic hydroxyl groups in its molecule, (C) an inorganic filler, and (D) a curing accelerator:



wherein each of R1 and R2 represents a hydrogen atom or a hydrocarbon group with 4 or less carbon atoms and may be the same or different; and 'n' represents a mean value that is a positive number of from 0 to 5; in the formula (1).